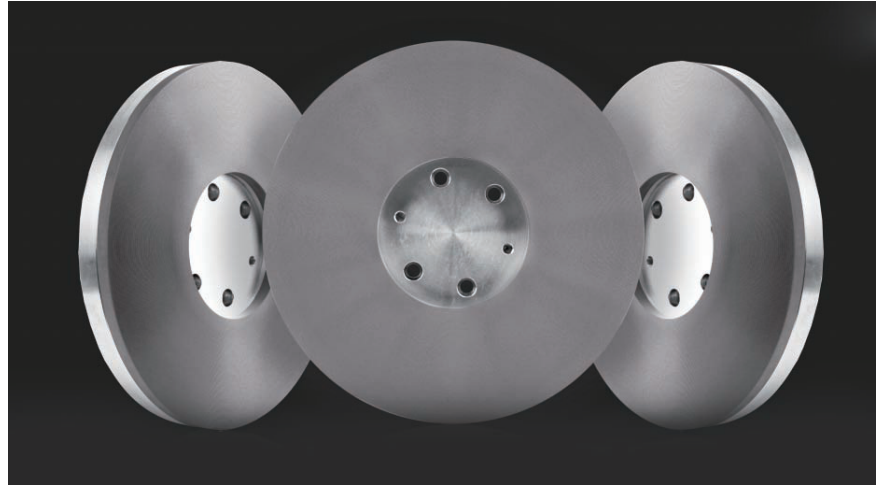


# IRON-RESIN PLATE for Sapphire wafer (LED)



## Advantages

- Excellent ductility minimizes the damages on the surface of wafers
- Providing the process specific plate in terms of Cut rate, Life time, and thermal stability
- Best solution for high-Precision polishing that requires zero defects on the surface of sapphire

## Application

- Patterned sapphire wafer
- Bare sapphire wafer
- Bare silicon wafer

## Specifications

| Application    | Outer Diameter( mm )                                                  | Inner Diameter( mm ) | Thickness( mm ) | Cut rate( mm ) |
|----------------|-----------------------------------------------------------------------|----------------------|-----------------|----------------|
| Sapphire wafer | Ø510~Ø1100                                                            | Ø 50~ Ø 500          | 12~25           | 2.5~5.0        |
| Lapping        | - Plate dimensions and cut rate can adjusted upon customers' demands. |                      |                 |                |

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## Performance Data

| Parameters      | Conditions                               |
|-----------------|------------------------------------------|
| Pressure        | 400 g/cm <sup>2</sup>                    |
| Plate velocity  | 90 rpm                                   |
| Polisher        | Single head type                         |
| Wafer           | 4 inch single crystalline sapphire wafer |
| Plate           | Copper - Resin Plate<br>Iron-Resin Plate |
| Slurry          | Primary diameter 3 μm                    |
| Slurry flowrate | 4 ml/min                                 |

